

2N5109

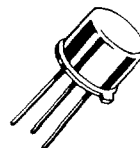
The RF Line

NPN SILICON HIGH-FREQUENCY TRANSISTOR

... designed specifically for broadband applications requiring good linearity. Useable as a high frequency current mode switch to 200 mA.

- Low Noise Figure — @ $f = 200$ MHz
NF = 3.0 dB (Typ)
- High Current-Gain — Bandwidth Product —
 $f_T = 1200$ MHz (Min) @ $I_C = 50$ mAdc

1.2 GHz @ 50 mAdc
**HIGH FREQUENCY
TRANSISTOR**
NPN SILICON



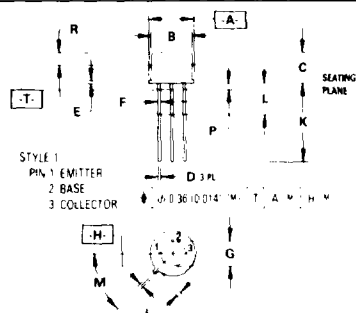
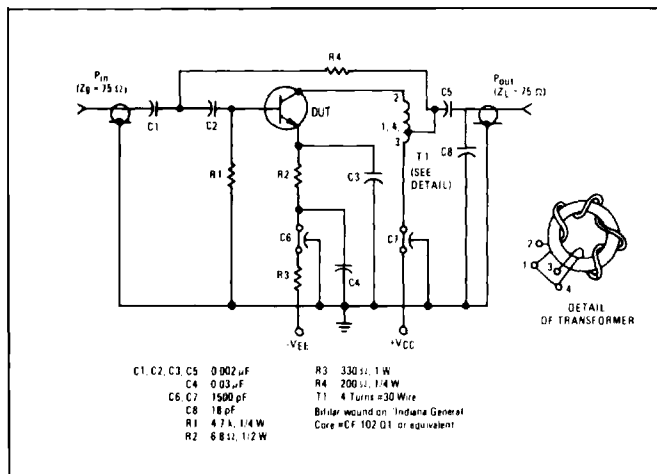
***MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V_{CE0}	20	Vdc
Collector-Base Voltage	V_{CB0}	40	Vdc
Emitter-Base Voltage	V_{EB0}	3.0	Vdc
Base Current — Continuous	I_B	400	mAdc
Collector Current — Continuous	I_C	400	mAdc
Total Device Dissipation @ $T_C = 75^\circ\text{C}$ (1) Derate above 25°C	P_D	2.5 20	Watt mW/ $^\circ\text{C}$
Storage Temperature Range	T_{stg}	-65 to +200	$^\circ\text{C}$

(1) Total Device Dissipation at $T_A = 25^\circ\text{C}$ is 1.0 Watt.

* Indicates JEDEC Registered Data.

**FIGURE 1 — RF AMPLIFIER FOR VOLTAGE
GAIN TEST CIRCUIT**



NOTES

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982
2. CONTROLLING DIMENSION: INCH
3. DIMENSION J MEASURED FROM DIMENSION A MAXIMUM
4. DIMENSION B SHALL NOT VARY MORE THAN 0.25 (0.010) IN ZONE R. THIS ZONE CONTROLLED FOR AUTOMATIC HANDLING
5. DIMENSION F APPLIES BETWEEN DIMENSION P AND L. DIMENSION D APPLIES BETWEEN DIMENSION L AND K. MINIMUM LEAD DIAMETER IS UNCONTROLLED IN DIMENSION P AND BEYOND DIMENSION K MINIMUM

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.51	9.39	0.335	0.370
B	7.75	8.50	0.305	0.335
C	6.10	6.60	0.240	0.260
D	0.41	0.53	0.016	0.021
E	0.23	1.04	0.009	0.041
F	0.41	0.48	0.016	0.019
G	5.08 BSC		0.200 BSC	
H	0.72	0.86	0.028	0.034
J	0.74	1.14	0.029	0.045
K	12.70	19.05	0.500	0.750
L	6.35		0.250	
M	45 BSC		45 BSC	
P	1.27		0.050	
R	2.54		0.100	

**CASE 79-04
TO-205AD
(TO-39)**

2N5109

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
* OFF CHARACTERISTICS					
Collector-Emitter Sustaining Voltage ($I_C = 5.0\text{ mA}$, $I_B = 0$)	$V_{CE0(sus)}$	20	—	—	Vdc
Collector-Emitter Sustaining Voltage (1) ($I_C = 5.0\text{ mA}$, $R_{BE} = 10\ \Omega$)	$V_{CER(sus)}$	40	—	—	Vdc
Collector Cutoff Current ($V_{CE} = 15\text{ Vdc}$, $I_B = 0$)	I_{CEO}	—	—	20	μAdc
Collector Cutoff Current ($V_{CE} = 15\text{ Vdc}$, $V_{BE} = -1.5\text{ V}$, $T_C = 150^\circ\text{C}$)	I_{CEX}	—	—	5.0	mA
Collector Cutoff Current ($V_{CE} = 35\text{ Vdc}$, $V_{BE} = -1.5\text{ V}$)		—	—	5.0	mA
Emitter Cutoff Current ($V_{BE} = 3.0\text{ Vdc}$, $I_C = 0$)	I_{EBO}	—	—	100	μAdc

* ON CHARACTERISTICS

DC Current Gain ($I_C = 360\text{ mA}$, $V_{CE} = 5.0\text{ Vdc}$) ($I_C = 50\text{ mA}$, $V_{CE} = 15\text{ Vdc}$)	h_{FE}	5.0 40	— —	— 120	—
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DYNAMIC CHARACTERISTICS

* Current-Gain – Bandwidth Product ($I_C = 50\text{ mA}$, $V_{CE} = 15\text{ Vdc}$, $f = 200\text{ MHz}$)	f_T	1200	—	—	MHz
* Collector-Base Capacitance ($V_{CB} = 15\text{ Vdc}$, $I_E = 0$, $f = 1.0\text{ MHz}$)	C_{cb}	—	1.8	3.5	pF
Noise Figure ($I_C = 10\text{ mA}$, $V_{CE} = 15\text{ Vdc}$, $f = 200\text{ MHz}$) (Figure 2)	NF	—	3.0	—	dB

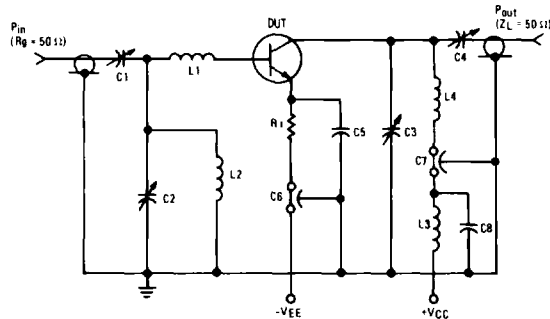
FUNCTIONAL TEST

* Common-Emitter Amplifier Voltage Gain (Figure 1) ($I_C = 50\text{ mA}$, $V_{CC} = 15\text{ Vdc}$, $f = 50$ to 216 MHz)	G_{ve}	11	—	—	dB
* Power Input (Figure 2) ($I_C = 50\text{ mA}$, $V_{CC} = 15\text{ Vdc}$, $R_S = 50\text{ ohms}$, $P_{out} = 1.26\text{ mW}$, $f = 200\text{ MHz}$)	P_{in}	—	—	0.1	mW

* Indicates JEDEC Registered Data.

(1) Pulsed thru a 25 mH Inductor; 50% Duty Cycle

FIGURE 2 – 200 MHz TEST CIRCUIT



$C1, C2, C3$ 1.0 – 30 pF
 $C4$ 1.0 – 20 pF
 $C5$ 10,000 pF
 $C6, C7$ 1,000 pF
 $C8$ 0.01 μF
 $L1$ 4-1/2 turns, No. 22 wire, 3/16" I.D.
 $L4$ 3-1/2 turns, No. 22 wire, 3/16" I.D.
 $L2, L3$ 0.82 μH RFC
 $R1$ 240 OHMS, 2 WATTS

FIGURE 3 – CURRENT GAIN – BANDWIDTH PRODUCT

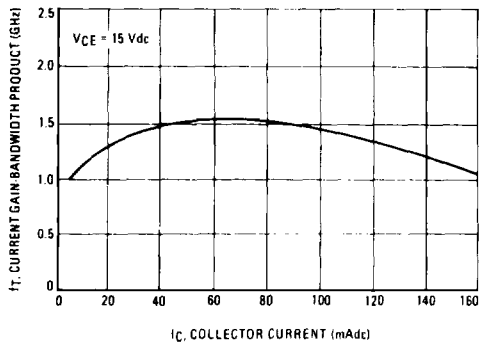


FIGURE 4 – COLLECTOR-BASE TIME CONSTANT

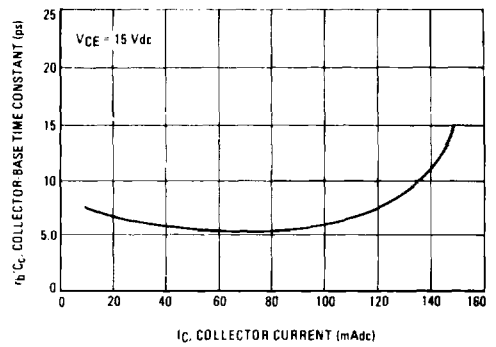


FIGURE 5 – SATURATION VOLTAGES

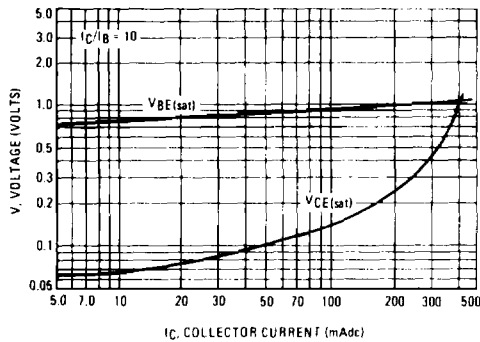


FIGURE 6 – CAPACITANCES versus REVERSE VOLTAGE

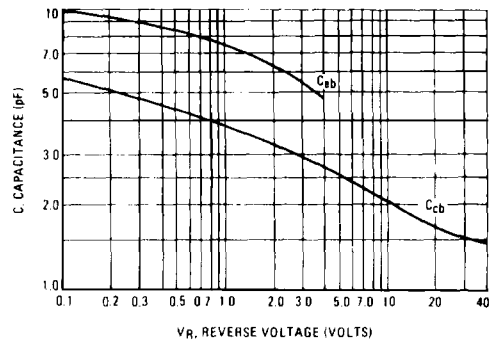


FIGURE 7 – INPUT ADMITTANCE versus FREQUENCY

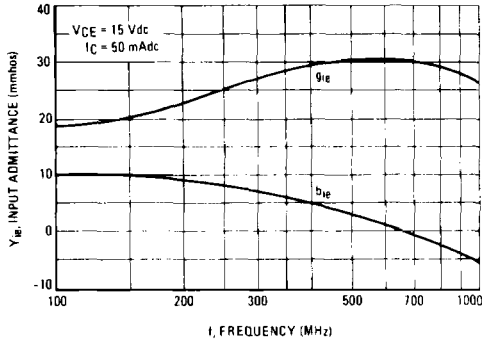


FIGURE 8 – INPUT ADMITTANCE versus COLLECTOR CURRENT

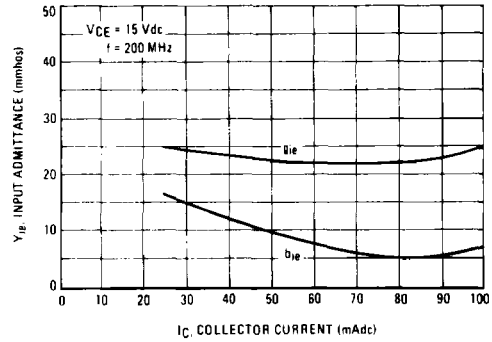


FIGURE 9 – REVERSE TRANSFER ADMITTANCE versus FREQUENCY

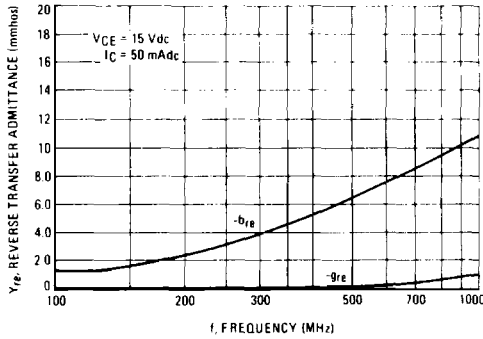


FIGURE 10 – REVERSE TRANSFER ADMITTANCE versus COLLECTOR CURRENT

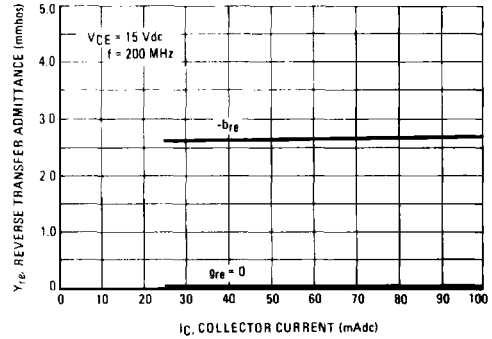


FIGURE 11 – FORWARD TRANSFER ADMITTANCE versus FREQUENCY

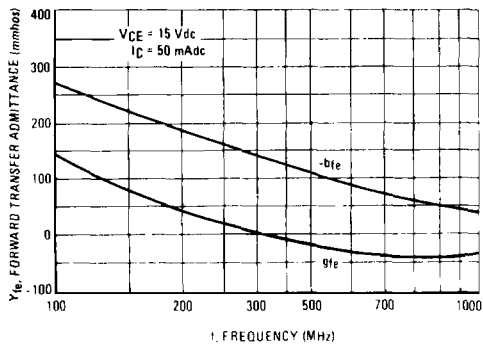


FIGURE 12 – FORWARD TRANSFER ADMITTANCE versus COLLECTOR CURRENT

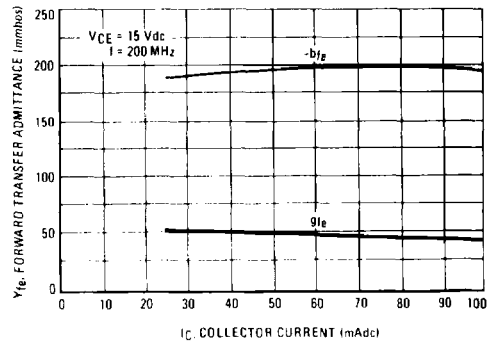


FIGURE 13 – OUTPUT ADMITTANCE versus FREQUENCY

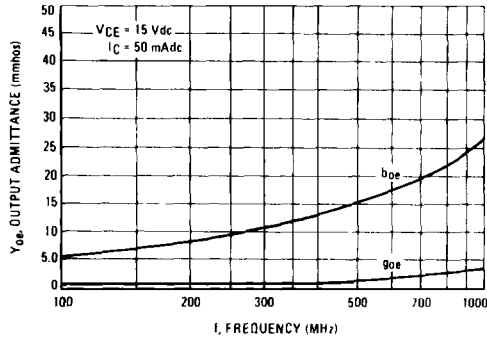


FIGURE 14 – OUTPUT ADMITTANCE versus COLLECTOR CURRENT

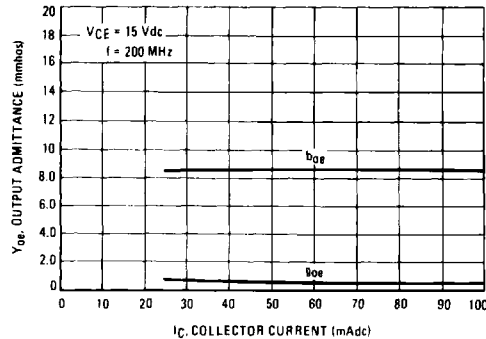


FIGURE 15 – INPUT REFLECTION COEFFICIENT versus FREQUENCY

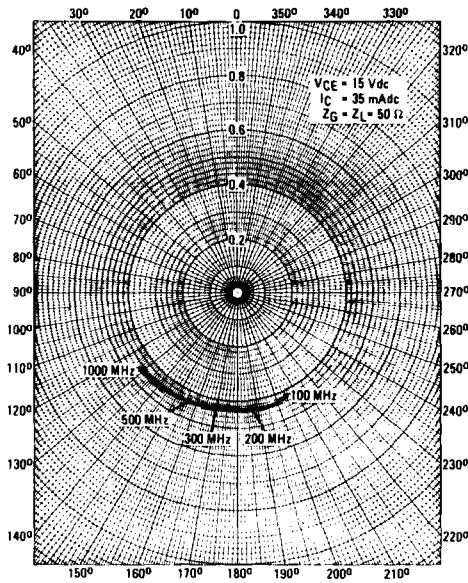


FIGURE 16 – OUTPUT REFLECTION COEFFICIENT versus FREQUENCY

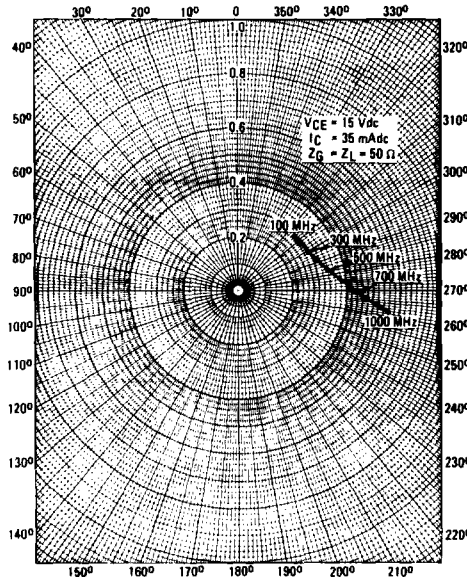


FIGURE 17 - REVERSE TRANSMISSION COEFFICIENT versus FREQUENCY

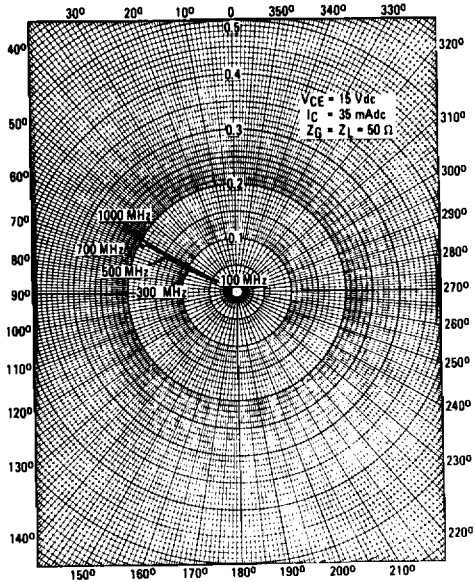


FIGURE 18 - FORWARD TRANSMISSION COEFFICIENT versus FREQUENCY

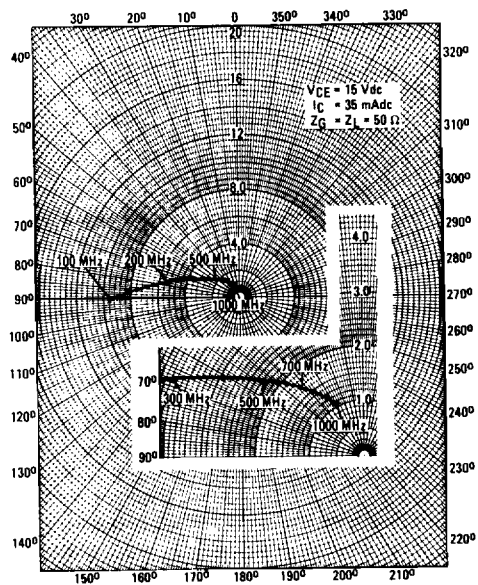


FIGURE 19 - INPUT REFLECTION COEFFICIENT AND OUTPUT REFLECTION COEFFICIENT versus FREQUENCY

